

SPECIFICATION

MODEL: <u>SLHNNWH511N0</u>

[Rank: (S0), (QA, QB, QC, QD), (G1, H1, J1)]

CUSTOMER:

CUSTOMER:				
CHECKED	APPROVED			

SAMSUNG LED					
DD AMAI	CHE	CKED	A DDD OVED		
DRAWN	Sales	CS	APPROVED		

SAMSUNG LED CO., LTD.
314. MAETAN 3-DONG, YEONGTONG-GU,
SUWON-SI,GYEONGGI-DO,KOREA,443-743



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1. Product Outline

1) Features

- Plastic Molded Lead Frame Type: 7.0 mm(L), 7.0 mm(W), 2.0 mm(T)
- Beam View Angle($\triangle \Theta$)* : 120 °
- · High Power / Brightness Chip & Long Time Reliability

2) Applications

- · Automotive Interior Lamp, Illumination etc.
- * View Angle describes the spatial intensity distribution and is the difference between the angles corresponding to 50% of the maximum intensity.

2. Absolute Maximum Rating

- Operation Forward Current 700 mA
- Reverse Current* 10 mA
- Thermal Resistance ($R_{th j-s}$) ····· \doteqdot 7 °C/W
- Operating Temperature Range (T_{OPR}) -40 °C ~ 100 °C
- Storage Temperature Range (T_{STG}) -40 °C \sim 110 °C
- LED Junction Temperature (T_i) ······ 125 ℃

3. Characteristics

1) Electrical properties $(T_i = 25 \text{ }^{\circ}\text{C})$

Parameter	Symbol	Condition	Rank	Min.	Тур.	Max.	Unit
Reverse Voltage	VR	$I_R = 10 \text{ mA}$	-	0.5	0.8	2.0	V
Forward Voltage	V _F	$I_F = 350 \text{ mA}$	S0	2.9	3.3	4.1	V

2) Chromaticity Coordinates (T_i = 25 °C)

Ra	ank	CCT(K)	Condition	CCx		Cx CCy					
	QA	6500~7000		0.3134	0.304	0.3106	0.3162	0.3242	0.308	0.2957	0.3056
Q1	QB	6000~6500	$I_{\text{F}} = \underset{\text{mA}}{350}$	0.3216	0.3134	0.3162	0.3231	0.3383	0.3242	0.3056	0.3178
QI	QC	5700~6000		0.3292	0.3216	0.3231	0.3292	0.351	0.3383	0.3178	0.3285
	QD	5400~5700		0.3354	0.3292	0.3292	0.3348	0.362	0.351	0.3285	0.3387

3) Luminous Flux $(T_j = 25 ^{\circ})$

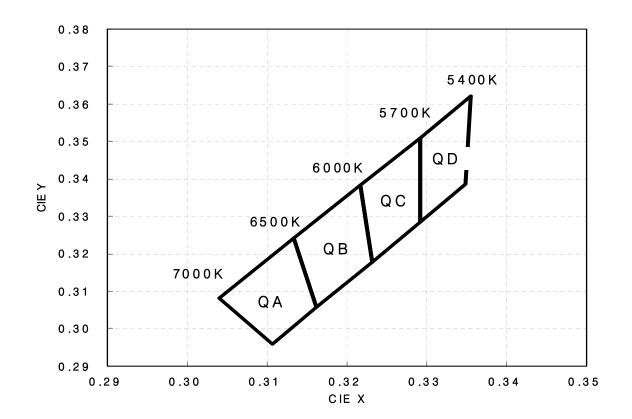
Ra	ınk	Symbol	Condition	Min.	Тур.	Max.	Unit
	G1			60		70	
G3	H1	Фу	$I_{\text{F}} = 350 \text{ mA}$	70		80	lm
	J1			80	-	90	

^{**} Tolerance : V_F : ± 0.1 , Φ_V : ± 10 %, CCx CCy : ± 0.02 , CCT : ± 0.5 %

^{*} Does not operate in the reverse direction.



4. Chromaticity Diagram





5. Typical Characteristic Graphs T_j = 25 ℃ Forward Current vs. Forward Voltage Relative Luminous Flux vs. Forward Current 1000 1.4 Forward Current[mA] 0.0 0 100 200 300 400 500 2.7 2.9 3.3 3.5 3.7 3.9 3.1 Forward Current[mA] Forward Voltage[V] Radiation Diagram Spectrum Distribution 1.0 380 480 680 780 -90 -60 90 580 Radiation Angle[°] Wavelength[nm] Derating Curve for 350mA ₩ Relative Luminous Flux vs. Ambient Temp. 400 1.1 Current 350 300 250 200 Relative Luminous Flux 33 °C/W -40 ℃/W Forward 100 50 ℃/W 50 0 0.8 25 40 70 85 100 115 130 20 30 50 60 70 80 90 Ambient Temperature[℃] Junction Temperature[℃] * Thermal Resistance Test Conditions - Junction to ambient thermal resistance - JEDEC Standard JESD 51-2,3 JESD 51-2: Integrated Circuits Thermal Test Method Environmental Conditions

JESD 51-3: Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Package

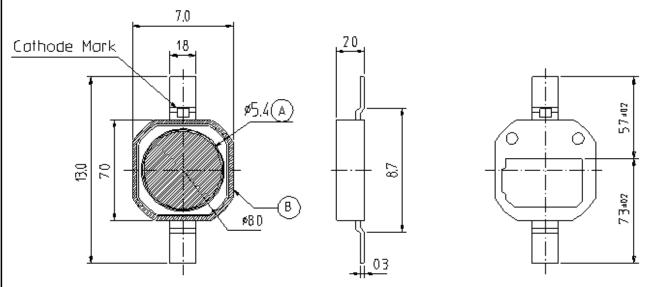
- Natural Convection (Still Air)



6. Outline Drawing and Dimension

Unit: mm

Tolerance: ±0.1



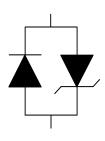
Pick and Place

- 1. Do not place pressure on the encapsulating resin ("A")

 It is recommended to use a pick & place nozzle with inside diameter of 5.8mm
- 2. The maximum compressing force is 15N on the polymer ("B")

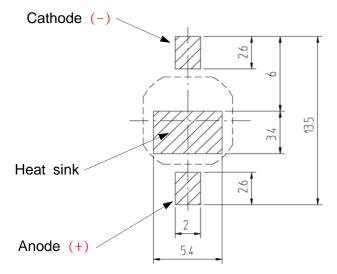
Circuit

Solder Pattern for Surface Mount



Cathode



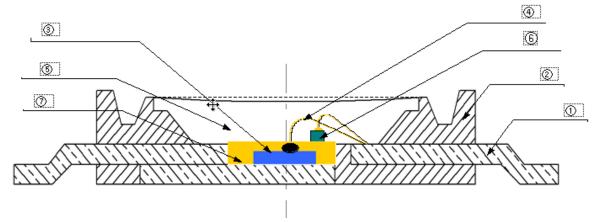


Remarks

Make sure that the heat sink is electrically connected to the Anode. Heat sink is to be soldered, If not, use the heat conductive adhesive.



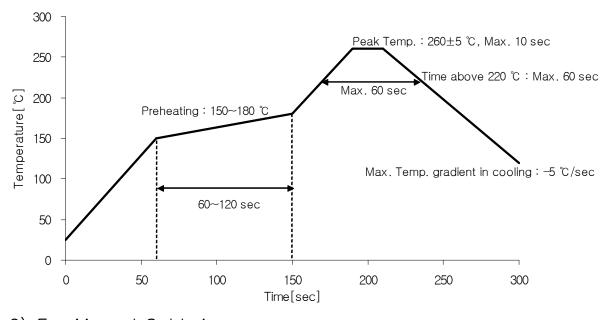
7. Package Structure



No	Component	Material
1	FRAME	Copper frame(Silver plated)
2	PACKAGE	Heat-resistant polymer
3	LED CHIP	SiC
4	WIRE	Gold wire
5	RESIN	Silicone
6	ZENER DIODE	Si
7	ENCAPSULATION RESIN	Silicone + Phosphor

8. Solder Conditions

1) Reflow Conditions (Pb-Free) Reflow Frequency: 2 time max.



2) For Manual Soldering

Not more than 5 seconds @Max. 300 °C, under soldering iron.



9. Reliability Test Items and Conditions

1) Test Items

Test Items	Test Conditions	Test Hours/Cycles
Room Temperature life test	25 °C, I _F = Max DC*	1,000 h
High Temperature humidity life test	85 ℃, 85 % RH, I _F = Max DC**	1,000 h
High Temperature life test	85 ℃, I _F = Max DC*	1,000 h
Low Temperature life test	-40 ℃, I _F = Max DC*	1,000 h
High Temperature Storage	110 ℃	1,000 h
Low Temperature Storage	-40 °C	1,000 h
Thermal Shock	-40 / 120 ℃, each 30 min	200 cycles
Temperature humidity Cycle On/Off test	-40 / 85 ℃, each 20 min, 100 min transfer Power On/off each 5 min, DC 350 ^{mA}	100 cycles
Reflow (Pb-Free)	Peak 260±5 ℃ for 10 sec	3 times
Mechanical Shock	1500 G, 0.5 msec, 5 time, each 6 axis	_
Variable Vibration Frequency	100~2000~100 Hz, 20 G, 20 m/s², Sweep time 1 min, X.Y.Z each axis	_
ESD(HBM)	R_1 R_2 R_2 R_3 R_4 R_5	3 times (± 5 kV)
Salt Atmosphere	35 ℃, 5 %, 분무 : 8 h, 방치 : 16 h,	2 cycle
Drop	1.2 m, Concrete,	3 time
Solderability	400 °C, 5 sec	1 time
Lead Strength	1 lb, 30 sec	_
Lead Fatigue	1 lb, 3 x 45 ° bend	_

^{*} Max. DC current is depending on maximum current derating curve.



2) Criteria for Judging the Damage

Item	Symbol	Test Condition	Limit		
ILGIII	Syllibol	Test Condition	Min	Max	
Forward Voltage	VF	$I_F = 350 \text{ mA}$	_	U.S.L.*1.2	
Luminous Flux	Ф۷	$I_F = 350 \text{ mA}$	L.S.L.*0.5	_	

* U.S.L: Upper Standard Level, L.S.L: Lower Standard Level



10. Taping Dimension 2.00 ±0.1 4.00 ±0.1 0.30 ±0.05 Cathode + + + + Anode 12.00 ±0.1 2.32 ±0.1 Ø1.50Min LED Mounting Part Min.150 (No LED) Min.100 (No LED) 7.40 ±0.15 2.50 ±0.15 User Feed Direction START END

Symbol	Α	В	С	W1	W2
Dimension(mm)	330 ± 1	80 ± 1	25 ± 0.5	13 ± 0.3	29.5 ± 1

- (1) Quantity: 2,000 Pcs / 13" Reel.
- (2) Cumulative Tolerance: Cumulative Tolerance/10 pitches is less than ±0.2 mm
- (3) Adhesion Strength of Cover Tape: Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at 10 °C angle to be the carrier tape.
- (4) Packaging: P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package

11. Label Structure



Rank Code

/S0/: VF Rank (refer to page 3)

/SA/: Chromaticity Coordinate Rank, CIE (refer to page 3)

/H1/: Luminous Flux (refer to page 3)

12. Lot Number

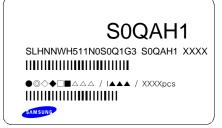
The Lot number is composed of the following characters

- ◎ ◇ ◆ □ △ △ △ / I ▲ ▲ ▲ / 2000 PCS
 - : Production Site (S:SAMSUNG LED, G:Gosin China)
 - : L (LED)
 - ♦ : Product State (A:Normality, B:Bulk, C:First Production, R:Reproduction, S:Sample)
 - ◆ : Year (S:2008, T:2009, U:2010...)
 - \square : Month (1 ~ 9, A, B)
 - \blacksquare : Day (1 ~ 9, A, B ~ V)
 - \triangle : SAMSUNG LED Product Number (1 ~ 999)
 - ▲ : Reel Number (1 ~ 999)

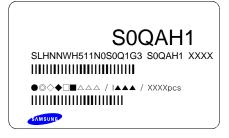


13. Reel Packing Structure

1) Reel



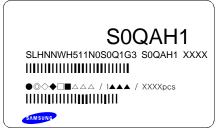
2) Aluminum Bag

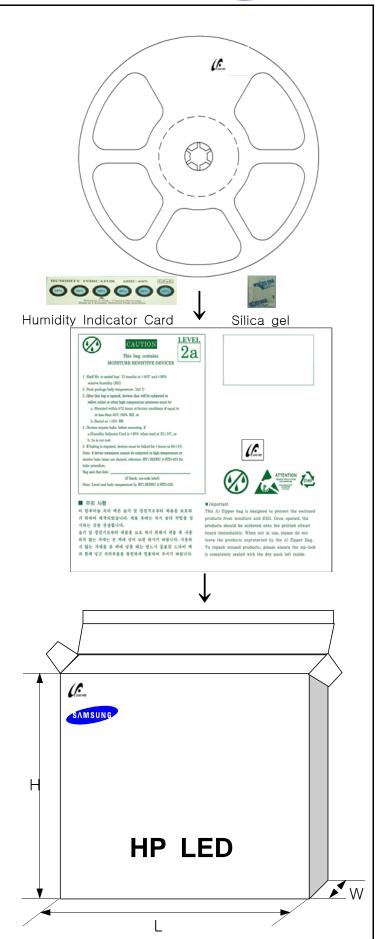


3) Inner Box

Material: Paper(SW3B(B))

TYPE	SIZE(mm)				
ITFE	L	W	Н		
13inch	335	45	335		



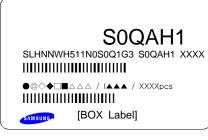


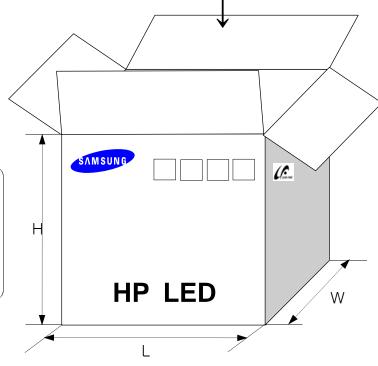




Material : Paper(SW3B(B))

TYPE	SIZE(mm)			
ITFC	اــ	W	Ι	
13inch	350	350	350	







14. Precaution for Use

- 1) For over-current-proof function, customers are recommended to apply resistors to prevent sudden change of the current caused by slight shift of the voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When washing is required, IPA is recommended to use.
- 3) When the LEDs illuminate, operating current should be decided after considering the ambient maximum temperature.
- 4) LEDs must be stored in a clean environment. If the LEDs are to be stored for 3 months or more after being shipped from SAMSUNG LED, they should be packed by a sealed container with nitrogen gas injected. (Shelf life of sealed bags: 12 months, temp. 0~40°C, 20~70%RH)
- 5) After storage bag is open, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 168 hours (7days) at an assembly line with a condition of no more than $30\,^{\circ}\text{C}/60\,^{\circ}\text{RH}$,
 - b. Stored at <10% RH.
- 6) Repack unused Products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60% at 23 ± 5 °C.
- 8) Devices must be baked for 24hours at $65\pm5^{\circ}$ °C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
 - If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices.
 - Damaged LEDs may show some unusual characteristics such as increase in leak current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.



	SAMSUNG LED
10)	When handling LED with tweezers, the LED Should only be held by the polymer body, not by the encapsulant or LENS.
11)	The use of appropriate nozzle for the LED recommended. For the recommended nozzle size, refer to the figure at the below.
12)	Do not stack assembled PCBs together. Since silicone is a soft material, abrasion between two PCB assembled with silicone encapsulated LED might cause catastrophic failure of the LEDs due to damage to encapsulant and wire and LED detachment.



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15. Hazard Substance Analysis



Test Report No. F690501/LF-CTSAYA08-04155

To: SAMSUNG ELECTRO-MECHANICS CO., LTD.

314, Maetan3-dong Yeongtong-gu Suwon-city GYEONGGI-DO 442-373 Korea

The following merchandise was submitted and identified by the client as:

Product Name : LED

SGS File No. : AYA08-04155

Received Date : February 04, 2008

Test Performing Date : February 05, 2008

Test Performed : SGS Testing Korea tested the sample(s) selected by applicant with following results

Test Results : For further details, please refer to following page(s)

Comments: The sampling and testing was performed only for the part indicated in the photo without

disassembly by the applicant's specific request.

SGS Testing Korea Co. Ltd.

Issued Date: February 11, 2008

Pluto Kim Monet Jeong

Billy Oh / Testing Person

Jeff Jang / Chemical Lab Mgr

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: AYA08-04155.001 Sample No.

: LED Sample Description

: 7070 No Lens (Cool White) Item No./Part No.

Heavy Metals

Test Items	Unit	Test Method	MDL	Results
Cadmium (Cd)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996), ICP	0.5	N.D.
Lead (Pb)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996), ICP	5	N.D.
Mercury (Hg)	mg/kg	US EPA 3052(1996), US EPA 6010B(1996), ICP	2	N.D.
Hexavalent Chromium (Cr VI)	mg/kg	US EPA 3060A(1996), US EPA 7196A(1992), UV	1	N.D.

Flame Retardants-PBBs/PBDEs

Test Items	Unit	Test Method	MDL	Results
Monobromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Dibromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tribromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tetrabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Pentabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Hexabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Heptabrom obiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Octabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Nonabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Decabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Monobromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Dibromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tribromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tetrabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Pentabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Hexabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Heptabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Octabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Nonabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Decabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.

NOTE: (1) N.D. = Not detected.(<MDL)

(2) mg/kg = ppm (3) MDL = Method Detection Limit

(4) - = No regulation (5) ** = Qualitative analysis (No Unit)

(6) Negative = Undetectable / Positive = Detectable

F052 Version2





Test Report No. F690501/LF-CTSAYA08-04155

Issued Date: February 11, 2008 Page 3 of 3



*** End ***

NOTE: (1) N.D. = Not detected.(<MDL)

(2) mg/kg = ppm

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(5) ** = Qualitative analysis (No Unit)

(6) Negative = Undetectable / Positive = Detectable

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F052 Version2



Revision History

(Model	:	SLHNNWH511N0S0Q1G3)

Data		Author		
Date	Revision History	Drawn	Approved	
2009.08.06	Initial Approval	K.T Kim	H.K Kim	